TL592B
DIFFERENTIAL VIDEO AMPLIFIER

SLFS001A – JUNE 1985 – REVISED APRIL 1988

- **Adjustable Gain to 400 Typ**
- **No Frequency Compensation Required**
- **Low Noise . . . 3 μV Typ V_n**

description

This device is a monolithic two-stage video amplifier with differential inputs and differential outputs. It features internal series-shunt feedback that provides wide bandwidth, low phase distortion, and excellent gain stability. Emitter-follower outputs enable the device to drive capacitive loads. All stages are current-source biased to obtain high common-mode and supply-voltage rejection ratios.

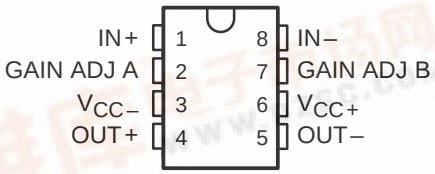
The differential gain is typically 400 when the gain adjust pins are connected together, or amplification may be adjusted for near 0 to 400 by the use of a single external resistor connected between the gain adjustment pins A and B. No external frequency-compensating components are required for any gain option.

The device is particularly useful in magnetic-tape or disk-file systems using phase or NRZ encoding and in high-speed thin-film or plated-wire memories. Other applications include general-purpose video and pulse amplifiers.

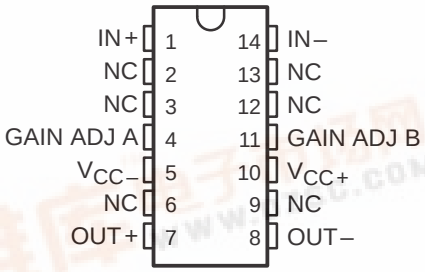
The device achieves low equivalent noise voltage through special processing and a new circuit layout incorporating input transistors with low base resistance.

The TL592B is characterized for operation from 0°C to 70°C.

D8† OR P PACKAGE
(TOP VIEW)

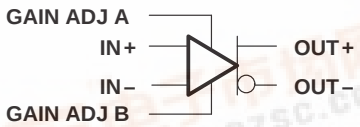


D14† OR N PACKAGE
(TOP VIEW)

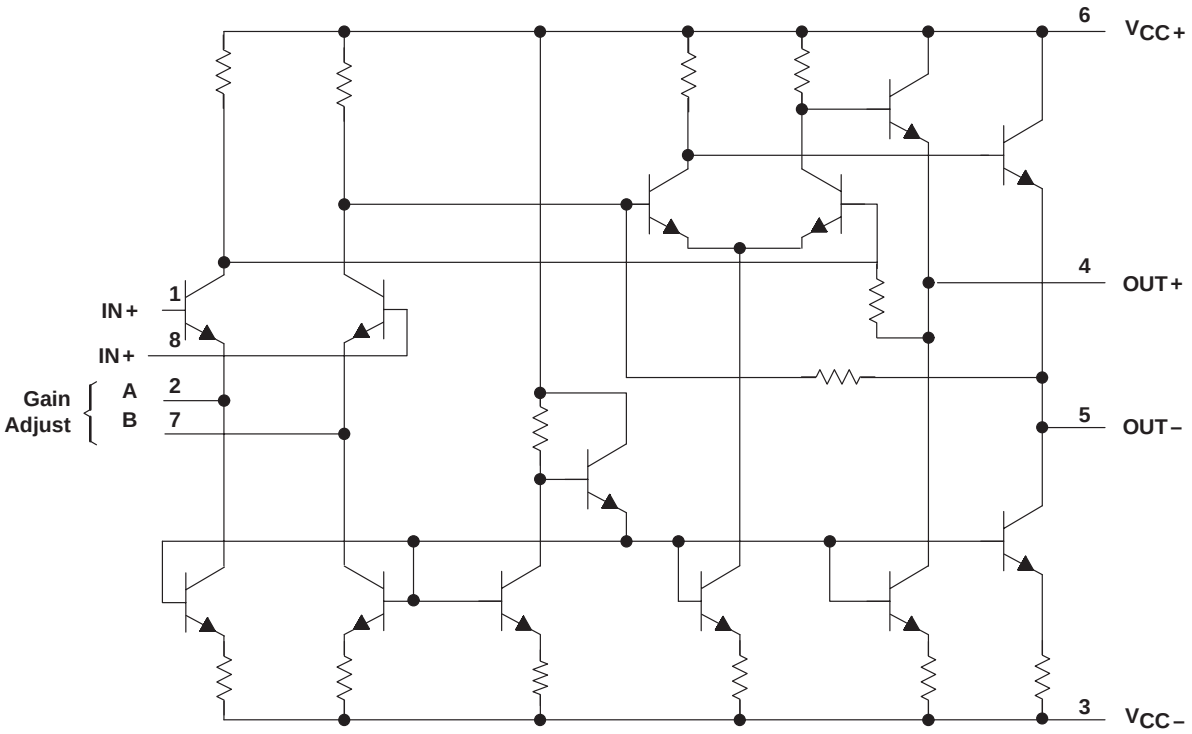


† D8 and D14 are the codes to differentiate the 8-pin and 14-pin versions, respectively.

symbol



schematic



Pin numbers are for D8 and P packages.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Supply voltage, V_{CC+} (see Note 1) . . . . . 8 V
Supply voltage, V_{CC-} . . . . . –8 V
Differential input voltage . . . . . ±5 V
Voltage range, any input . . . . . V_{CC+} to V_{CC-}
Output current . . . . . 10 mA
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

NOTES: 1. All voltage values except differential input voltages are with respect to the midpoint between V_{CC+} and V_{CC-}.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70°C$ POWER RATING
D8	530 mW	5.8 mW/°C	59°C	464 mW
D14	530 mW	N/A	N/A	530 mW
N	530 mW	N/A	N/A	530 mW
P	530 mW	N/A	N/A	530 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+}	3	6	8	V
Supply voltage, V_{CC-}	–3	–6	–8	V
Operating free-air temperature, T_A	0		70	°C

electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ±6 V, R_L = 2 kΩ (unless otherwise noted)

PARAMETER		TEST FIGURE	TEST CONDITIONS†		T_A	MIN	TYP	MAX	UNIT
A_{VD}	Large-signal differential voltage amplification	1	V_{OPP} = 3 V, R_{AB} = 0	R_L = 2 kΩ,	25°C	300	400	500	V/V
					0°C to 70°C	250		600	
A_{VD2}	Large-signal differential voltage amplification	1	V_{OPP} = 3 V, R_{AB} = 1 kΩ	R_L = 2 kΩ,	25°C		13		V/V
BW	Bandwidth (–3 dB)	2	V_{OPP} = 1 V,	R_{AB} = 0	25°C		50		MHz
I_{IO}	Input offset current				25°C		0.4	5	µA
					0°C to 70°C			6	
I_{IB}	Input bias current				25°C		9	30	µA
					0°C to 70°C			40	
V_{ICR}	Common-mode input voltage range	3			25°C	±1			V
					0°C to 70°C	±1			
V_{OC}	Common-mode output voltage	1	R_L = ∞		25°C	2.4	2.9	3.4	V
V_{OO}	Output offset voltage	1	V_{ID} = 0, R_L = ∞	R_{AB} = ∞,	25°C		0.35	0.75	V
					0°C to 70°C			1.5	
V_{OPP}	Peak-to-peak output voltage swing	1	R_L = 2 kΩ,	R_{AB} = 0	25°C	3	4		V
					0°C to 70°C	2.8			
r_i	Input resistance		V_{OD} = 1 V,	R_{AB} = 0	25°C		4		kΩ
					0°C to 70°C		3.6		
r_o	Output resistance				0°C to 70°C			30	Ω
C_i	Input capacitance				25°C		5		pF
CMRR	Common-mode rejection ratio	3	V_{IC} = ±1 V, R_{AB} = 0	f = 100 kHz	25°C	60	86		dB
				f = 5 MHz			60		
				f = 100 kHz	0°C to 70°C	50			
				f = 5 MHz			60		
k_{SVR}	Supply voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)	4	ΔV_{CC+} = ± 0.5 V, ΔV_{CC-} = ± 0.5 V,	R_{AB} = 0	25°C	50	70		dB
					0°C to 70°C	50			
V_n	Broadband equivalent input noise voltage	4	BW = 1 kHz to 10 MHz		25°C		3		µV
t_{pd}	Propagation delay time	2	ΔV_O = 1 V		25°C		7.5		ns
t_r	Rise time	2	ΔV_O = 1 V		25°C		10.5		ns
$I_{sink(max)}$	Maximum output sink current		V_{ID} = 1 V,	V_O = 3 V		3	4		mA
I_{CC}	Supply current		No load,	No signal	25°C		18	24	mA
					0°C to 70°C			27	

† R_{AB} is the gain-adjustment resistor connected between gain-adjust pins A and B. If not specified for a particular parameter, its value is irrelevant to that parameter.

PARAMETER MEASUREMENT INFORMATION

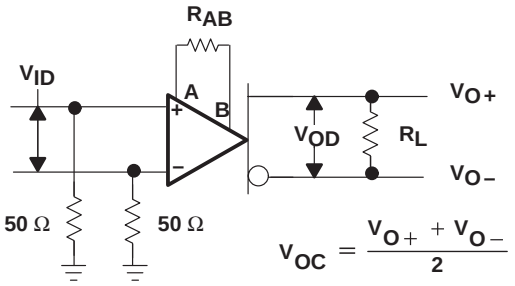


Figure 1

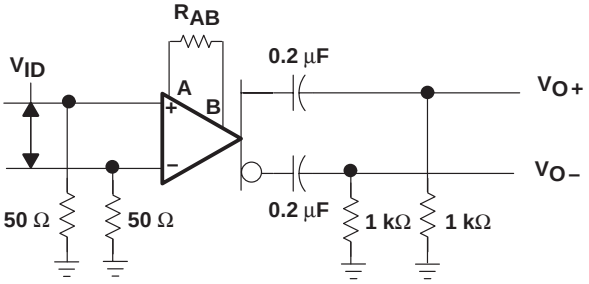


Figure 2

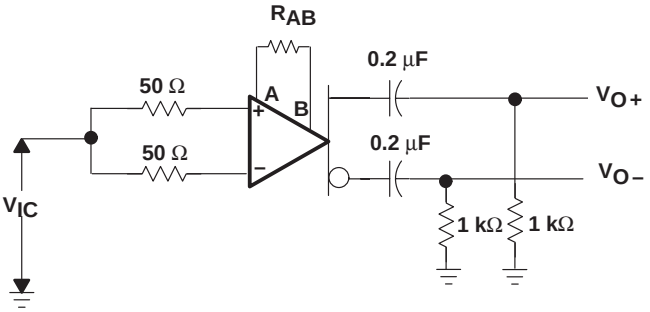


Figure 3

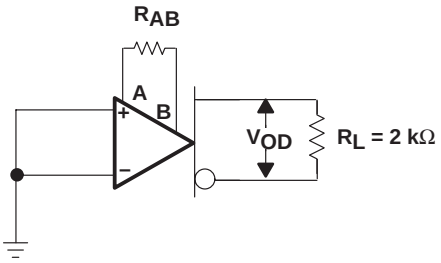


Figure 4

TYPICAL CHARACTERISTICS

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs SUPPLY VOLTAGE

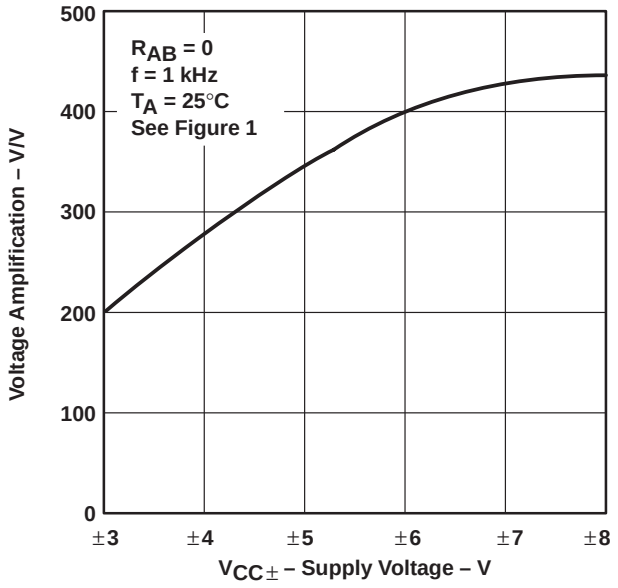


Figure 5

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs GAIN-ADJUSTMENT RESISTANCE

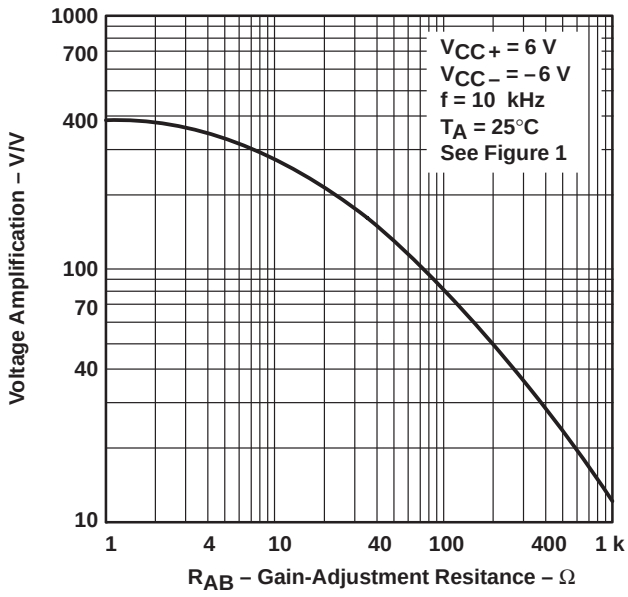


Figure 6

SUPPLY CURRENT vs SUPPLY VOLTAGE

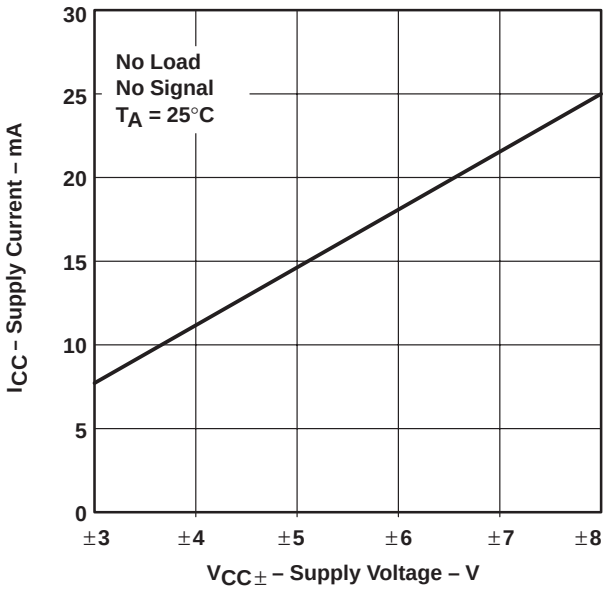


Figure 7

PACKAGE OPTION ADDENDUM

18-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TL592B-8D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL592B-8DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
TL592BI-8D	OBSOLETE	SOIC	D	8		None	Call TI	Call TI
TL592BN	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
TL592BP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL592BPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM

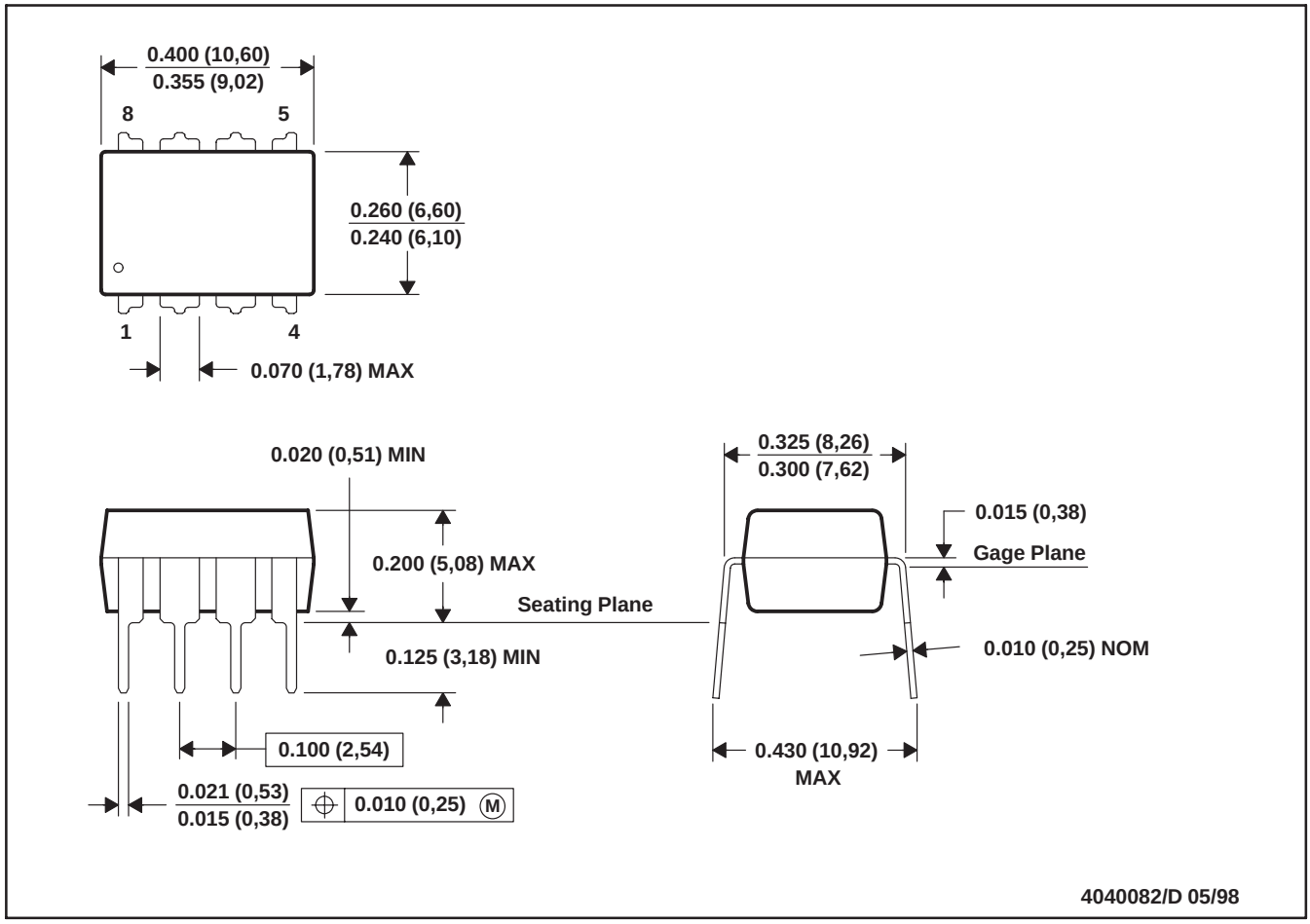
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

MPDI001A – JANUARY 1995 – REVISED JUNE 1999

P (R-PDIP-T8) **PLASTIC DUAL-IN-LINE**

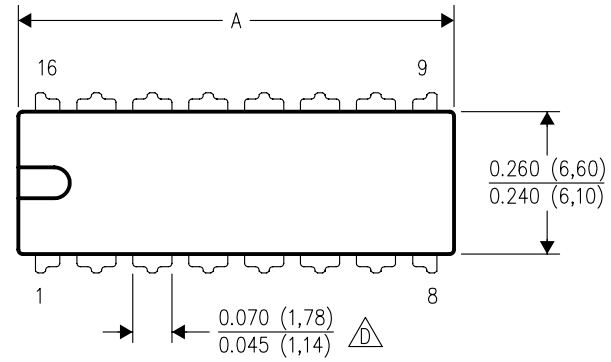


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

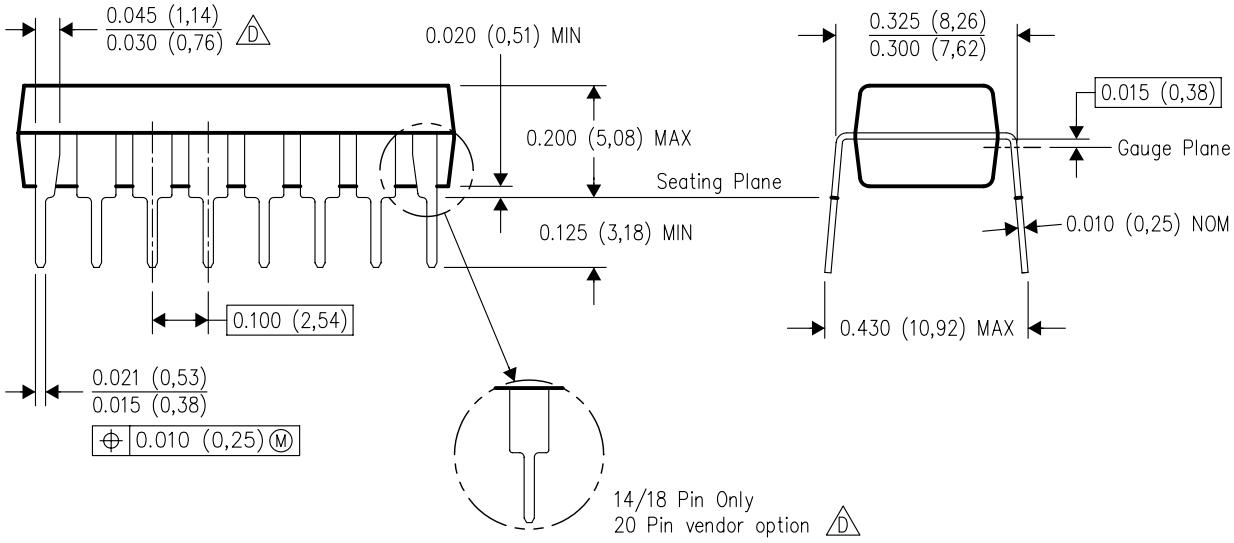
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



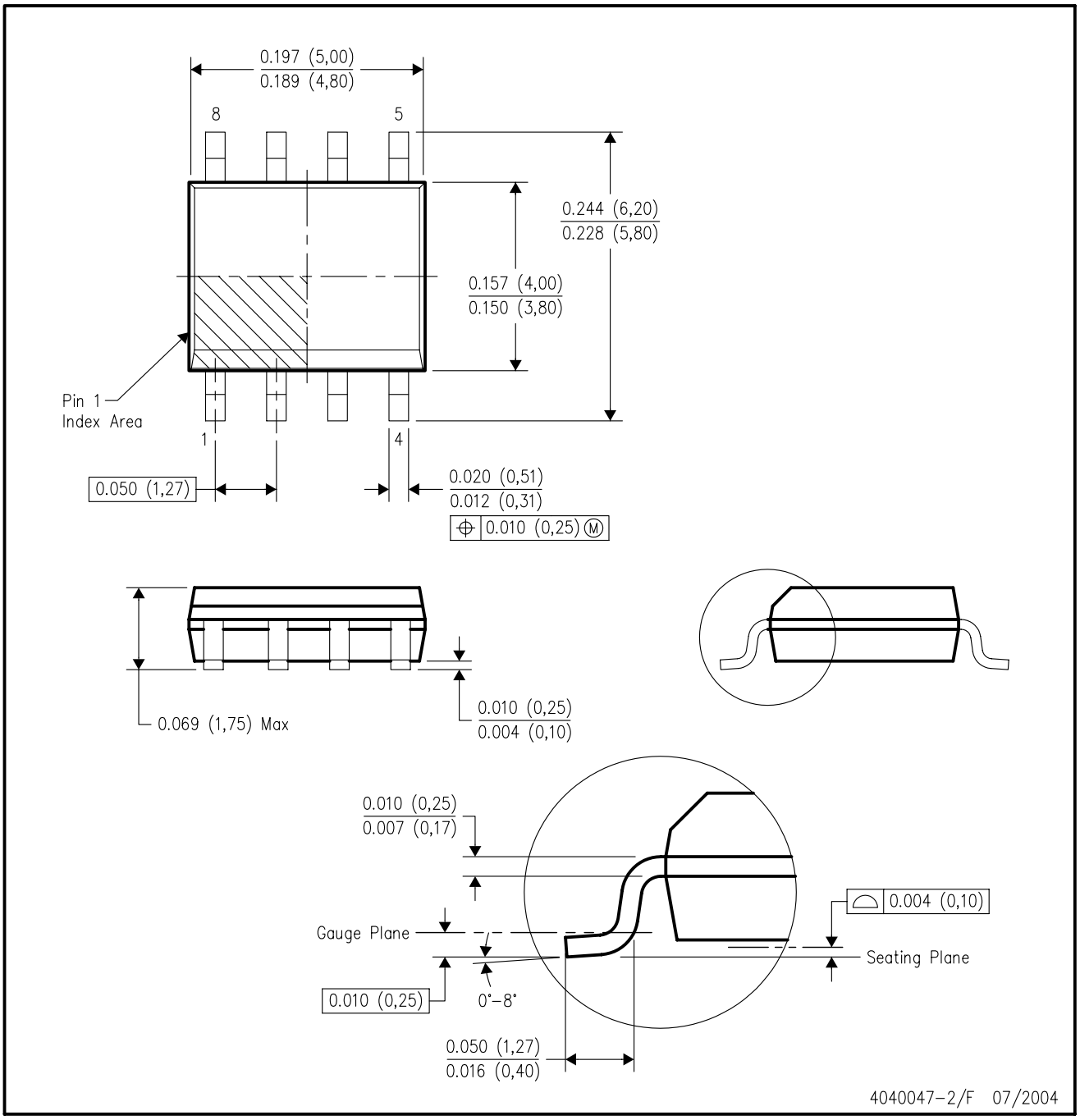
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

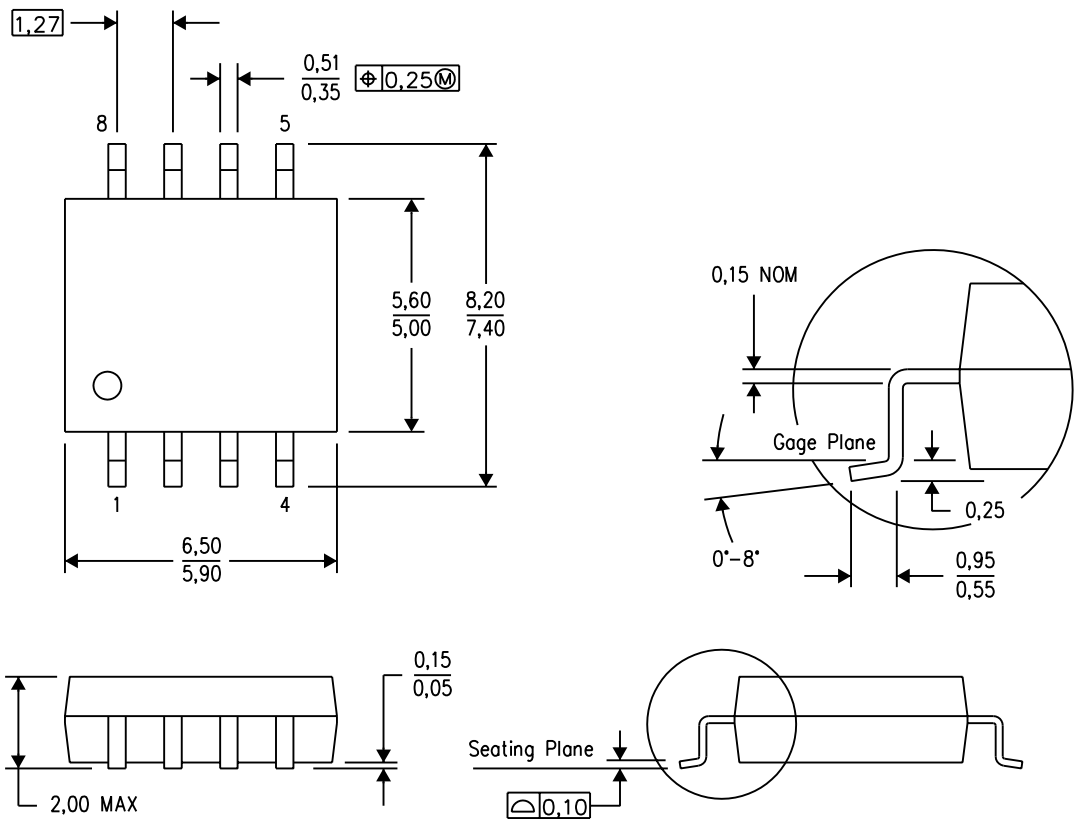
D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



4040063/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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Mailing Address: Texas Instruments
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